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April 1st, 2010 Renesas Electronics Corporation

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DATA SHEET

BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC3237TK$

LOW NOISE WIDE BAND SILICON GERMANIUM MMIC AMPLIFIER FOR MOBILE COMMUNICATIONS

DESCRIPTION

The μ PC3237TK is a silicon germanium (SiGe) monolithic integrated circuit designed as low noise amplifier for the mobile digital TV etc. This device exhibits low noise figure and high power gain characteristics.

This package is 6-pin lead-less minimold, suitable for surface mount.

This IC is manufactured using our 50 GHz fmax UHS2 (Ultra High Speed Process) SiGe bipolar process.

FEATURES

٠	Supply voltage	: Vcc = 2.4 to 3.3 V (2.8 V TYP.)
•	Low current consumption	: Icc = 5 mA TYP. @ Vcc = 2.8 V
•	Low Noise	: NF = 1.4 dB TYP. @ f = 470 MHz
		: NF = 1.5 dB TYP. @ f = 770 MHz
•	Power gain	: G _P = 15.3 dB TYP. @ f = 470 MHz
		: G _P = 13.5 dB TYP. @ f = 770 MHz
•	High-density surface mounting	: 6-pin lead-less minimold package $(1.5 \times 1.1 \times 0.55 \text{ mm})$

APPLICATIONS

• Low noise amplifier for the mobile digital TV etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μΡC3237TK-E2	μPC3237TK-E2-A	6-pin lead-less minimold (1511 PKG) (Pb-Free)	6N	 Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 5 kpcs/reel

Remark To order evaluation samples, please contact your nearby sales office Part number for sample order: μ PC3237TK

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Pin Name

NC

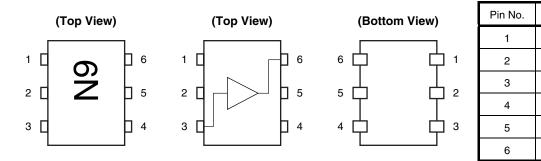
GND

Vcc

GND

OUTPUT

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions		Ratings	Unit
Supply Voltage	Vcc	T _A = +25°C		3.6	V
Circuit Current	lcc	T _A = +25°C	5	10	mA
Power Dissipation	PD	T _A = +85°C	Note	203	mW
Operating Ambient Temperature	TA			-40 to +85	°C
Storage Temperature	T _{stg}			-55 to +150	°C
Input Power	Pin	T _A = +25°C	6	+8	dBm

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	2.4	2.8	3.3	V
Operating Ambient Temperature	TA	-40	+25	+85	°C

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	lcc	No input signal	3.5	5	7	mA
Power Gain 1	G⊵1	f = 470 MHz, P _{in} = -30 dBm	13.0	15.3	17.5	dB
Power Gain 2	G⊧2	f = 770 MHz, P _{in} = -30 dBm	11.0	13.5	16.0	dB
Noise Figure 1	NF1	f = 470 MHz	-	1.4	1.9	dB
Noise Figure 2	NF2	f = 770 MHz	-	1.5	2.0	dB
Input Return Loss 1	RLin1	f = 470 MHz, P _{in} = -30 dBm	6.5	9.5	-	dB
Input Return Loss 2	RLin2	f = 770 MHz, P _{in} = -30 dBm	5.5	8.5	-	dB
Output Return Loss 1	RLout1	f = 470 MHz, P _{in} = -30 dBm	9	14	-	dB
Output Return Loss 2	RLout2	f = 770 MHz, P _{in} = -30 dBm	10	15	_	dB
Isolation 1	ISL1	f = 470 MHz, P _{in} = -30 dBm	17	22	-	dB
Isolation 2	ISL2	f = 770 MHz, Pin = -30 dBm	16	21	-	dB
Gain 1 dB Compression Output Power 1	PO (1 dB) 1	f = 470 MHz	-8	-5.5	_	dBm
Gain 1 dB Compression Output Power 2	Po (1 dB) 2	f = 770 MHz	-8	-5.5	-	dBm

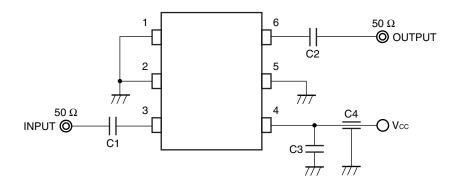
ELECTRICAL CHARACTERISTICS (T_A = +25°C, V_{CC} = 2.8 V, Z_S = Z_L = 50 Ω , unless otherwise specified)

STANDARD CHARACTERISTICS FOR REFERENCE

 $(T_A = +25^{\circ}C, V_{CC} = 2.8 V, Z_S = Z_L = 50 \Omega, unless otherwise specified)$

Parameter	Symbol	Test Conditions	Reference Value	Unit
Saturated Output Power 1	Po (sat) 1	f = 470 MHz, Pin = +2 dBm	+1.3	dBm
Saturated Output Power 2	Po (sat) 2	f = 770 MHz, Pin = +2 dBm	+1.3	dBm
Input 3rd Order Distortion Intercept Point 1	IIP ₃ 1	f1 = 470 MHz, f2 = 471 MHz	-10.5	dBm
Input 3rd Order Distortion Intercept Point 2	IIP₃2	f1 = 770 MHz, f2 = 771 MHz	-9.5	dBm
Output 3rd Order Distortion Intercept Point 1	OIP₃1	f1 = 470 MHz, f2 = 471 MHz	+4.8	dBm
Output 3rd Order Distortion Intercept Point 2	OIP ₃ 2	f1 = 770 MHz, f2 = 771 MHz	+4.0	dBm
K factor 1	K1	f = 470 MHz	1.15	-
K factor 2	K2	f = 770 MHz	1.20	-

TEST CIRCUIT



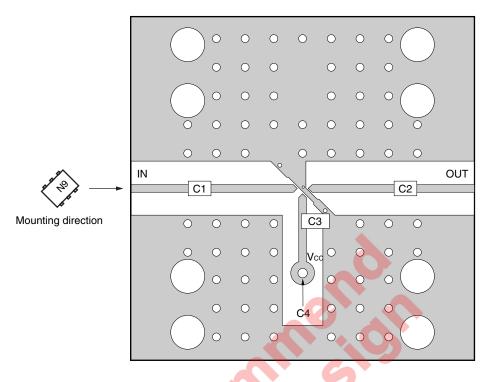
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

ELECTRICA	AL CHARACTERISTICS		
	Туре	Value	
C1, C2	Chip Capacitor	100 pF	
C3	Chip Capacitor	1 000 pF	
C4	Feed-through Capacitor	1 000 pF	

Data Sheet PU10675EJ01V0DS

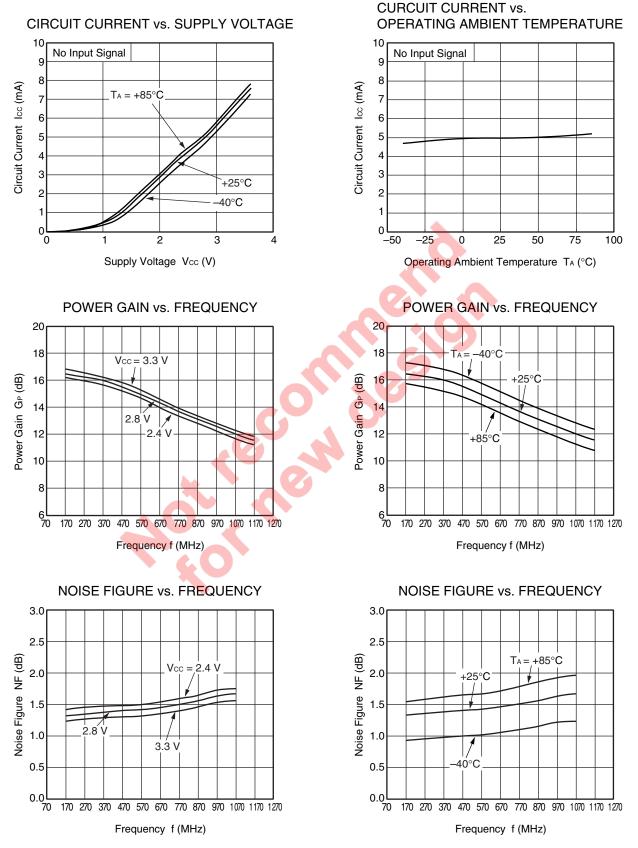
ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



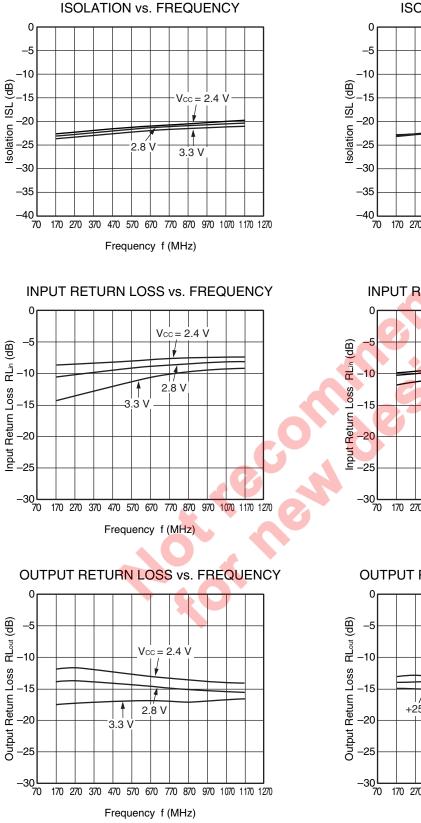
Notes

- 1. $30 \times 30 \times 0.4$ mm double sided copper clad FR-4 board.
- 2. Back side: GND pattern
- 3. Au plated on pattern
- 4. •O: Through holes

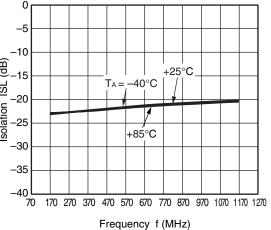
TYPICAL CHARACTERISTICS (TA = +25°C, Vcc = 2.8 V, Zs = ZL = 50 Ω , unless otherwise specified)



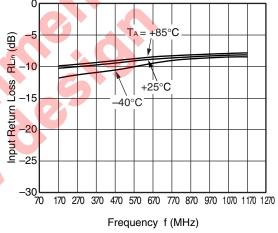
Remark The graphs indicate nominal characteristics.



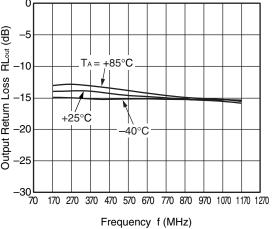
ISOLATION vs. FREQUENCY



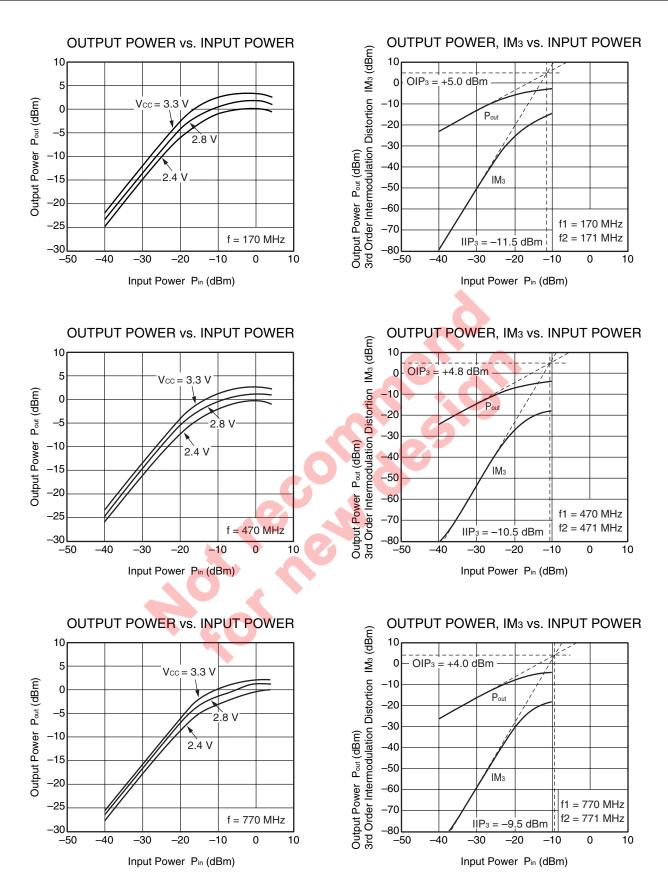
INPUT RETURN LOSS vs. FREQUENCY



OUTPUT RETURN LOSS vs. FREQUENCY

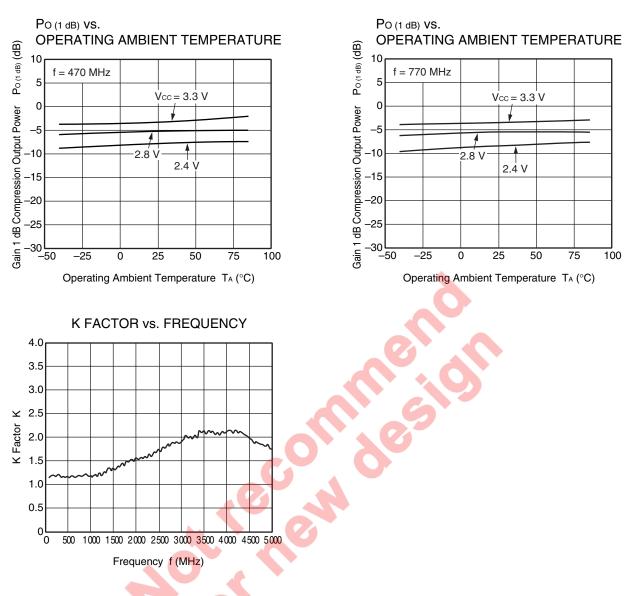


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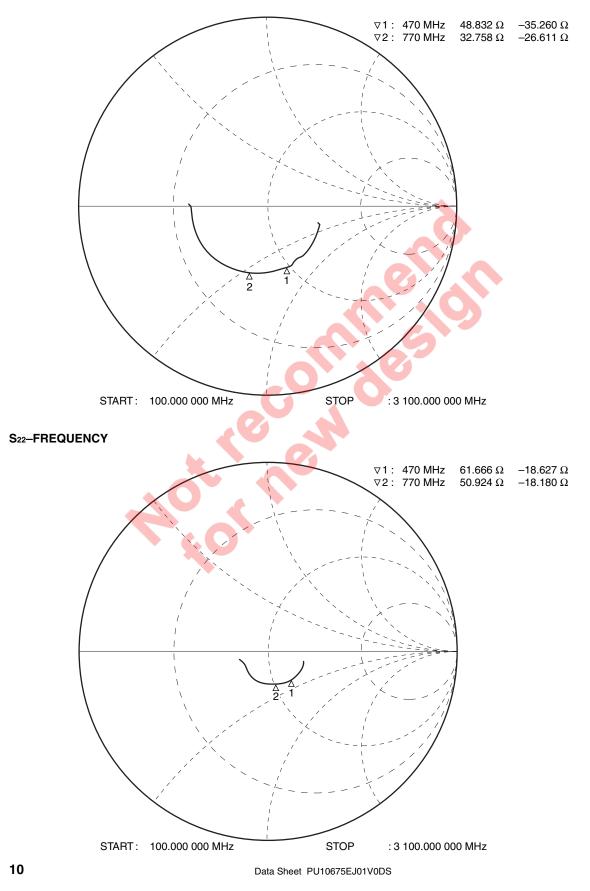
Data Sheet PU10675EJ01V0DS



Remark The graphs indicate nominal characteristics.

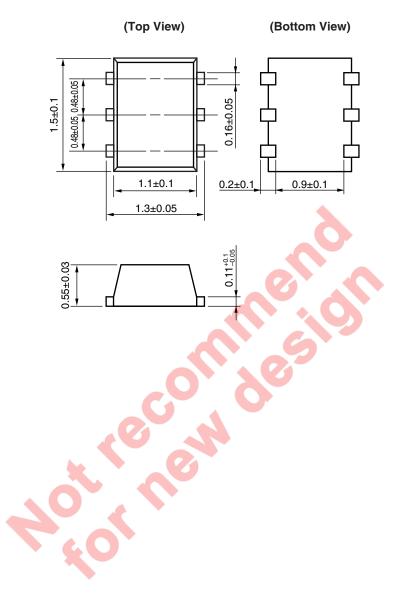
S-PARAMETERS (TA = +25°C, Vcc = 2.8 V, monitored at connector on board)

S11-FREQUENCY



PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to the $V_{\rm CC}$ line.
- (4) The DC cut capacitor should be attached to Input and Output pin.
- (5) Pin 1 (NC) should be connected to the ground pattern.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol	
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below	IR260
	Time at peak temperature	: 10 seconds or less	
	Time at temperature of 220°C or higher	: 60 seconds or less	
	Preheating time at 120 to 180°C	: 120±30 seconds	
	Maximum number of reflow processes	: 3 times	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below	WS260
	Time at peak temperature	: 10 seconds or less	
	Preheating temperature (package surface temperature)	: 120°C or below	
	Maximum number of flow processes	: 1 time	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below	HS350
	Soldering time (per side of device)	: 3 seconds or less	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	

Caution Do not use different soldering methods together (except for partial heating).

2.0

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